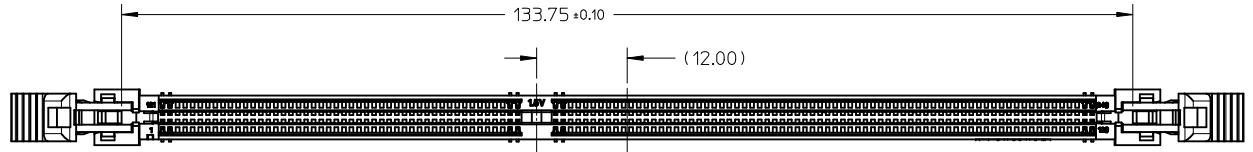


NOTES:

1. MATERIAL : HOUSING - HIGH TEMP LCP, GLASS FILLED, UL 94V-0  
COLOUR : SEE TABLE.  
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0  
COLOUR : SEE TABLE.  
TERMINAL : COPPER ALLOY.
2. FINISHES - SEE TABLE ON SHEET 2.
3. PRODUCT SPECIFICATION : SEE TABLE.
4. PRODUCT SHALL BE PACKED IN TRAY - SEE SHEET 5.
5. CARD SLOT ACCEPTS 1.27+0.10MM MODULE THICKNESS (MEASURED FROM P.C. PADS).

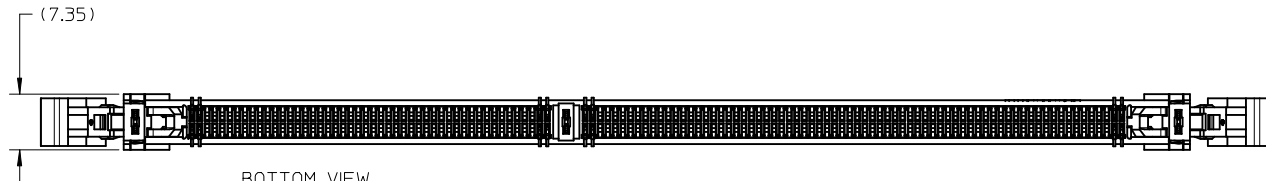
- MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
- MODULE SEATING PLANE FROM TOP OF PCB.
- KEEP OUT ZONE RESERVED FOR LATCH.
- KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDED LATCHES IN OPENING POSITION) IS MOUNTED ON THE PCB.
- KEEP OUT ZONE AS PER JEDEC SO-007.
- FORKLOCK DETAIL VIEW.

REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	DESCRIPTION QUALITY SYMBOLS = 0 = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
				MM ONLY	NTS	METRIC				
				mm	INCH	DRAWN BY	DATE	TITLE		
				4 PLACES	± ---	± ---	DWLEE01	2007/05/07	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT	
		3 PLACES	± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED			
		2 PLACES	± 0.2	± ---	TYANG01	2007/07/06				
		1 PLACE	± ---	± ---	APPROVED BY	DATE	DOCUMENT NO.			
		ANGULAR ± 1 °		SHLENI		2007/07/06	SD-78156-001			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE TABLE		SHEET NO.		
				SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		1 OF 6		
				A3						



TOP VIEW  
(LATCHES ARE IN OPENING POSITION)

CENTER LINE OF 133.75 FEATURE

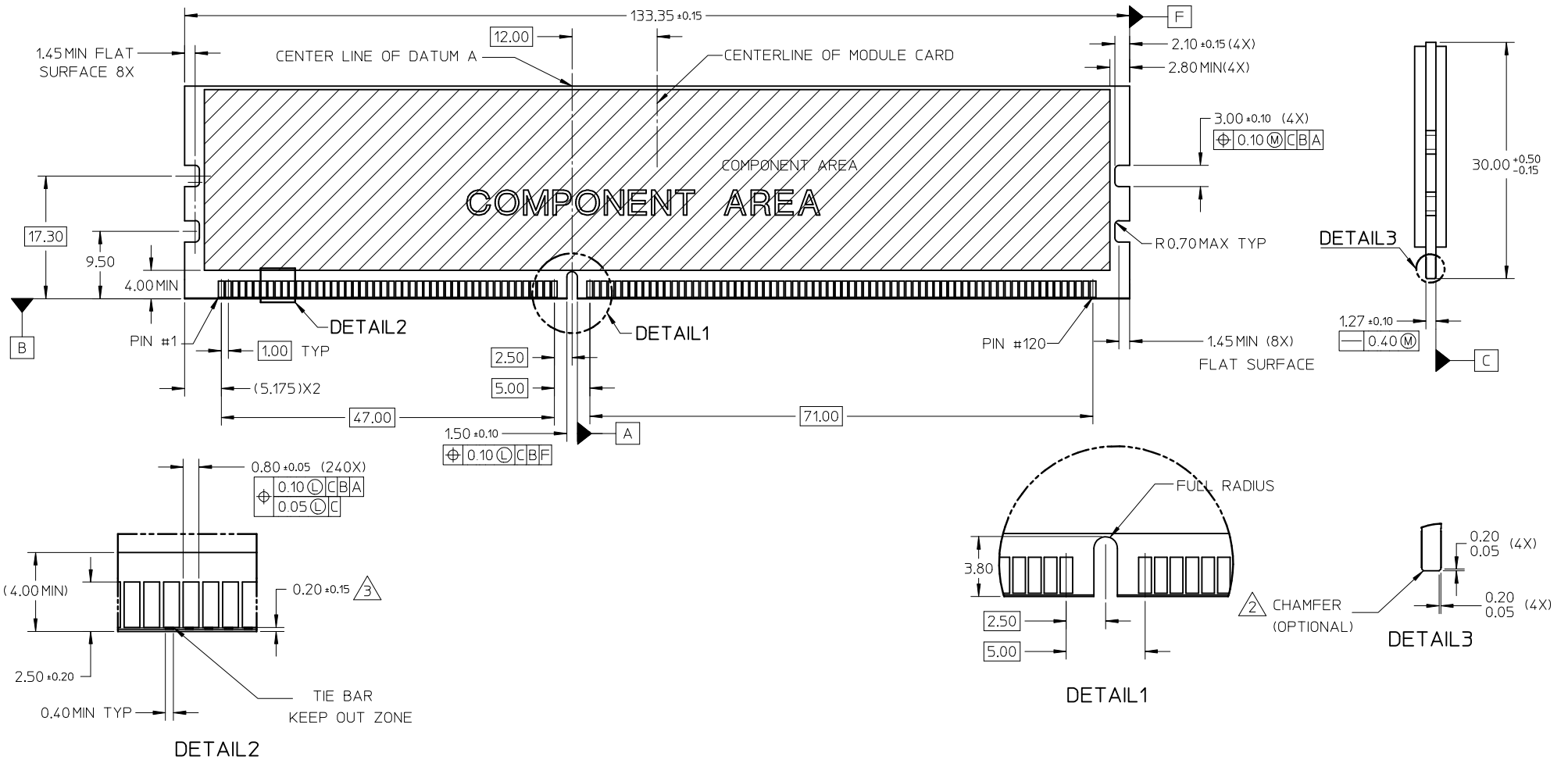


BOTTOM VIEW  
(LATCHES ARE IN OPENING POSITION)

REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		▼=0 ◻=0	mm	INCH	DRAWN BY DWLEE01	DATE 2007/05/07	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT				
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY YTYANG01	DATE 2007/07/06	MOLEX INCORPORATED DOCUMENT NO. SD-78156-001 SHEET NO. 2 OF 6				
			2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	APPROVED BY SHLENI	DATE 2007/07/06					
A1		ANGULAR ± 1 °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS											

10 9 8 7 6 5 4 3 2 1

MODULE CARD  
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS  
 (JEDEC MO-269, ISSUE A, 12/05)



- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:  
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL.  
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
  - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS.
  - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	DESCRIPTION A1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION															
		$\nabla=0$ $\text{C}=0$	<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.2</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.2	± ---	1 PLACE	± ---	± ---	MM ONLY	NTS	METRIC	
			mm	INCH																		
		4 PLACES	± ---	± ---																		
3 PLACES	± ---	± ---																				
2 PLACES	± 0.2	± ---																				
1 PLACE	± ---	± ---																				
		DRAWN BY: DWLEE01 DATE: 2007/05/07 CHECKED BY: YTYANG01 DATE: 2007/07/06 APPROVED BY: SHLENI DATE: 2007/07/06	TITLE	DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL SMT																		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-78156-001	SHEET NO. 3 OF 6																	

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

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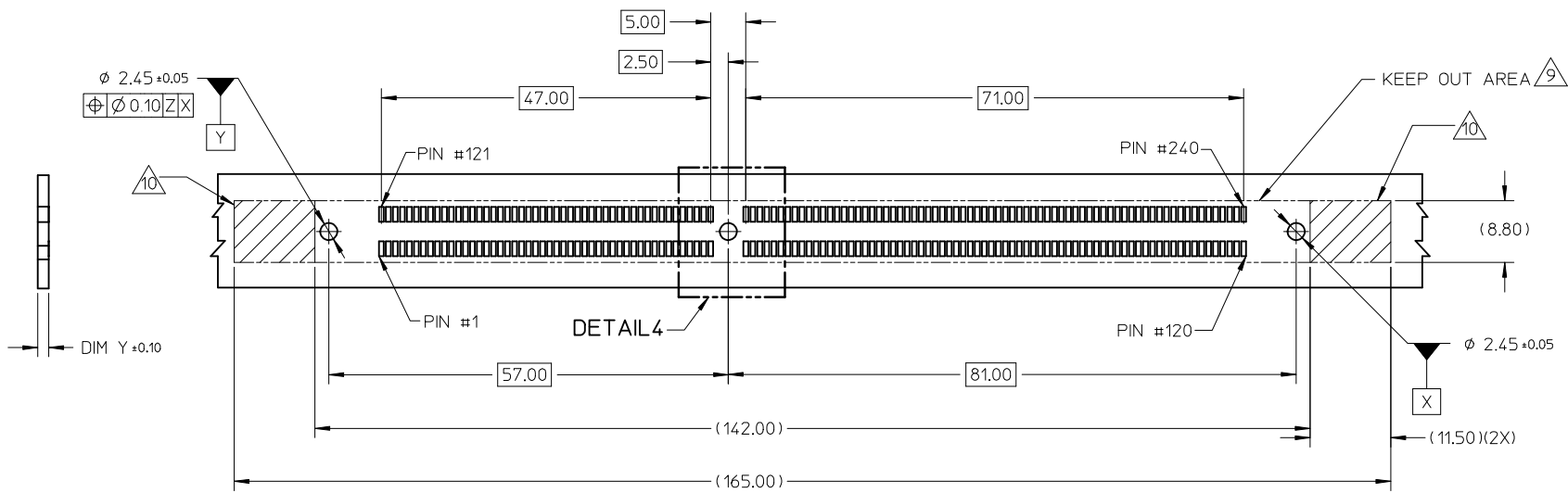
E

D

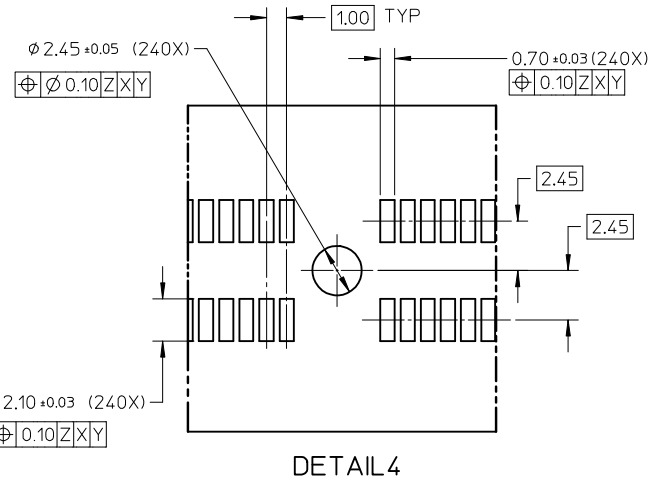
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B

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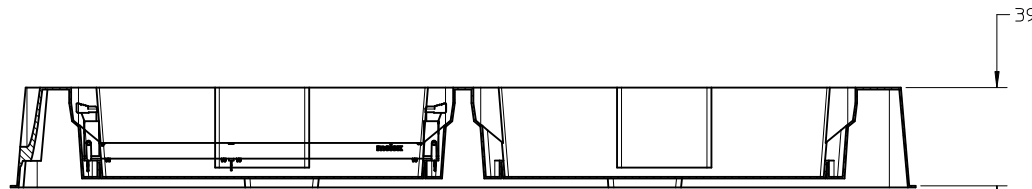
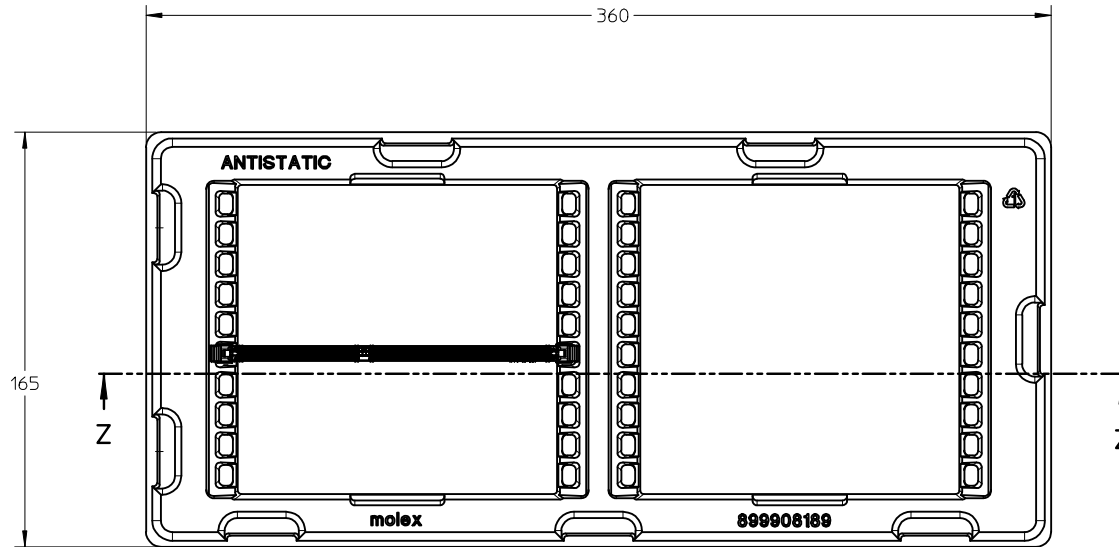
RECOMMENDED PCB THICKNESS 1.57MM TO 3.18MM  
 RECOMMENDED STENCIL THICKNESS = 150 MICROMETERS



REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$\nabla=0$ $\square=0$	4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY DWLEE01	DATE 2007/05/07	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT			
		ANGULAR ± 1 °		CHECKED BY YTYANG01	DATE 2007/07/06	APPROVED BY SHLENI 2007/07/06			
				MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78156-001		SHEET NO. 4 OF 6	
A1	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

# VIEW OF PACKAGING TRAY



SECTION Z-Z

NOTE:

1. CAVITY QTY ; 20PCS

<b>REVISED</b> EC NO: S2009-0916 DRW:CMTEO CHKD:CGTAN APPR:SHLENI	2009/06/26 2009/06/26 2009/06/26	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	DRAWN BY DWLEE01	DATE 2007/05/07	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT				
			ANGULAR ± 1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		CHECKED BY YTYANG01	DATE 2007/07/06	MOLEX INCORPORATED		
			A1	SEE TABLE		APPROVED BY SHLENI	DATE 2007/07/06	DOCUMENT NO. SD-78156-001	SHEET NO. 5 OF 6	

PART NO.	VOLTAGE KEY POS.	DIM X	PCB THICKNESS DIM Y (mm)	PLATING OPTION	HOUSING COLOUR	LATCH COLOUR	PRODUCT SPEC.
78156-0001	CENTER (1.5)	3.94	1.57 - 3.18	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK	PS-78156-001
78156-0003		3.94	1.57 - 3.18		NATURAL (IVORY)	NATURAL (IVORY)	
78156-0005		3.94	1.57 - 3.18		BLACK	NATURAL (IVORY)	
78156-0102		3.94	1.57 - 3.18	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	NATURAL (IVORY)	NATURAL (IVORY)	PS-78156-002

REVISED EC NO: S2009-0916 DRWN:CMTEO CHKD:CGTAN APPR:SHLENI	2009/06/26 2009/06/26 2009/06/26	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ◻=0		mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	MM ONLY	NTS	METRIC	DRAWN BY: DWLEE01    DATE: 2007/05/07 CHECKED BY: YTYANG01    DATE: 2007/07/06 APPROVED BY: SHLENI    DATE: 2007/07/06	TITLE: DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	MOLEX INCORPORATED SD-78156-001 6 OF 6	
			SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				